



DDR4 DIMM

TE Internal #: 2309408-2
Small Outline (SO), 4 mm [.157 in] Stack Height, Right Angle
Module Orientation, 260 Position, .5 mm [.02 in] Centerline, DDR4
DIMM, SO DIMM Sockets

[View on TE.com >](#)

Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets > DDR4 SO DIMM Sockets



DRAM Type: **Small Outline (SO)**
Stack Height: **4 mm [.157 in]**
Module Orientation: **Right Angle**
Number of Positions: **260**
Centerline (Pitch): **.5 mm [.02 in]**

[All DDR4 SO DIMM Sockets \(39\)](#)

Features

Product Type Features

| | |
|-----------------------------------|-----------------------|
| Connector & Contact Terminates To | Printed Circuit Board |
| Connector System | Cable-to-Board |
| DRAM Type | Small Outline (SO) |

Configuration Features

| | |
|---------------------|-------------|
| Number of Keys | 1 |
| Number of Rows | 2 |
| Module Orientation | Right Angle |
| Number of Positions | 260 |

Electrical Characteristics

| | |
|--------------|-------|
| DRAM Voltage | 1.2 V |
|--------------|-------|

Signal Characteristics

| | |
|---------------|-------|
| SGRAM Voltage | 1.2 V |
|---------------|-------|

Body Features

| | |
|-------------------------|--------------------------------|
| Retention Post Location | Both Ends |
| Latch Material | High Temperature Thermoplastic |



| | |
|-------------------|-----------|
| Ejector Type | Locking |
| Ejector Location | Both Ends |
| Connector Profile | Low |

Contact Features

| | |
|--|----------------|
| Contact Current Rating (Max) | .5 A |
| Memory Socket Type | Memory Card |
| Contact Base Material | Copper Alloy |
| PCB Contact Termination Area Plating Material | Gold Flash |
| Contact Mating Area Plating Material | Gold (Au) |
| Contact Mating Area Plating Material Thickness | .127 µm[5 µin] |

Termination Features

| | |
|---------------------------|---------------|
| Insertion Style | Cam-In |
| Termination Method to PCB | Surface Mount |

Mechanical Attachment

| | |
|--------------------------|----------------|
| Connector Mounting Type | Board Mount |
| PCB Mount Retention Type | Solder Peg |
| Mating Alignment Type | Reverse Keying |
| PCB Mount Retention | With |

Housing Features

| | |
|--------------------|--------------------------------|
| Housing Material | High Temperature Thermoplastic |
| Housing Color | Black |
| Centerline (Pitch) | .5 mm[.02 in] |

Dimensions

| | |
|--------------------|-----------------|
| Stack Height | 4 mm[.157 in] |
| Row-to-Row Spacing | 8.2 mm[.322 in] |

Usage Conditions

| | |
|-----------------------------|---------------------------|
| Operating Temperature Range | -55 – 85 °C[-67 – 185 °F] |
|-----------------------------|---------------------------|

Operation/Application

| | |
|---------------------|-------|
| Circuit Application | Power |
|---------------------|-------|

Industry Standards

| | |
|------------------------|----------|
| UL Flammability Rating | UL 94V-0 |
|------------------------|----------|

Packaging Features



| | |
|--------------------|-------------|
| Packaging Quantity | 900 |
| Packaging Method | Tape & Reel |

Product Compliance

For compliance documentation, visit the product page on TE.com>

| | |
|---|---|
| EU RoHS Directive 2011/65/EU | Compliant |
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | 有害物质含量符合标准要求 No Restricted Substance(s) Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2025 (250) Candidate List Declared Against: JUNE 2025 (250) Does not contain REACH SVHC |
| Halogen Content | Low Halogen - Br, Cl, F < 900 ppm per homogenous material. Also BFR/CFR/PVC Free |
| Solder Process Capability | Reflow solder capable to 260°C |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) ‘Guidance on requirements for substances in articles’ posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Also in the Series | **DDR4 DIMM**

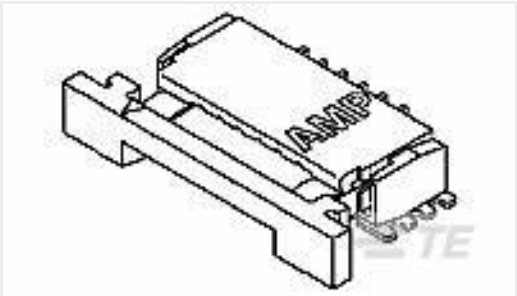


DIMM Sockets(13)



SO DIMM Sockets(39)

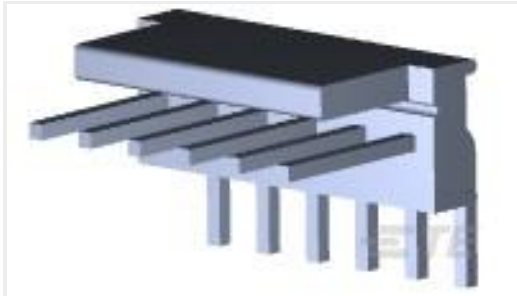
Customers Also Bought



TE Part #84952-9
1MM FPC HORZ.BTTM CONT.ASS.9P



TE Part #1-338086-6
6/6 INV.MOD.JACK



TE Part #640455-6
06P MTA100 HDR ASSY SQ R/A POL



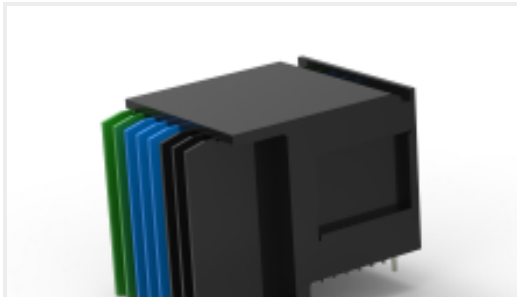
TE Part #3-640599-2
02P MTA156 CONN ASSY 18AWG
ORA



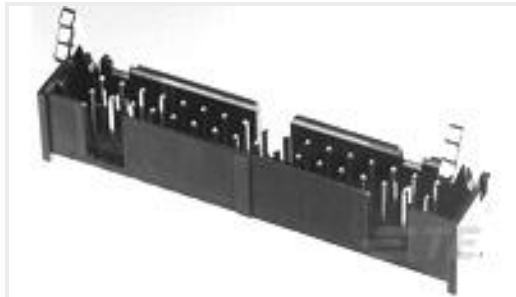
TE Part #643232-1
05P UMNL HDR ASSY R/A 94VO



TE Part #CAT-AX41-P1A
Small Signal Relay, Axicom P2
Standard



TE Part #1410189-4
MULTIGIG RT T2 7RW H-LFT,ET2



TE Part #1761606-7
IDC LOW PRO HDR 20P VERT LAT BLK



TE Part #2355825-4
Mezalok, Socket, 114 p, 12 mm, 50 Au,
LF

Documents

Product Drawings

DDR4 SODIMM 260P 4.0H RVS

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2309408-2_1.2d_dxf.zip



English

Customer View Model

[ENG_CVM_CVM_2309408-2_1.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2309408-2_1.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Specifications

Application Specification

English